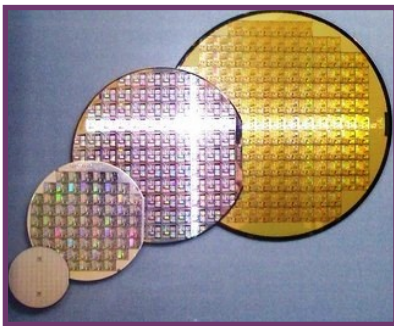
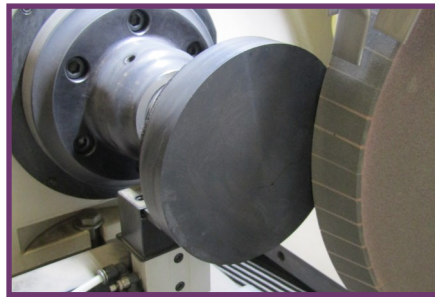
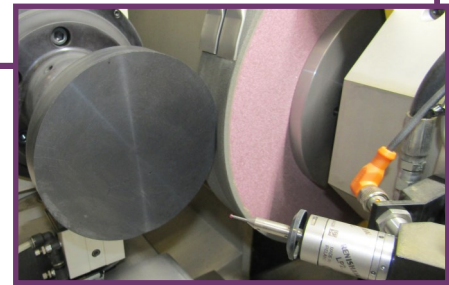


Midas 320A Dual Spindle SiC Grinder

A leader in Silicon Wafer technology has once again come to Weldon for solutions to their unique SiC grinding requirements.

In this application, an angular approach diamond grinding wheel is used to grind the OD & end face. In the same operation, a sub-spindle with a straight approach diamond wheel is presented to generate one

or two flats to specific C-axis coordinates relative to the grain structure of the crystal. The results are increased productivity, lower production cost, & consistently high quality.



Silicon wafer production cost is greatly reduced with Weldon's unique multi-spindle design allowing OD, Flat, & Face grinding in the same operation.

System Suppliers: *ATS* collet chuck, *Setco* sub-spindle, *Encyclon* coolant filtration system, *Renishaw* probe, *GII* electric dresser, *Dittel* acoustic emissions, *Koolant Koolers* tri-circuit spindle, linear motor, & coolant chiller, *SBS* automatic wheel balancer, *Heidenhain* linear & rotary glass scales, & *FANUC* 32i BT CNC control.



Weldon Solutions offers a full line of CNC OD, ID, & combination grinders. As a FANUC Robotics integrator Weldon can also address your machine tending, material removal, material handling, & packaging/palletizing needs.

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